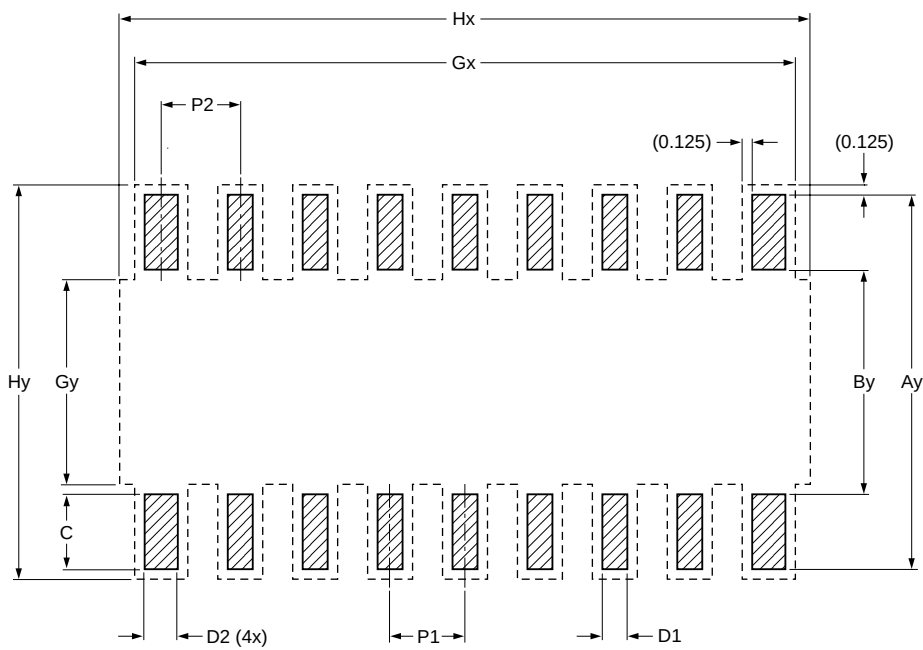


Footprint information for reflow soldering of TSSOP48 package

SOT480-1



Generic footprint pattern
Refer to the package outline drawing for actual layout

 solder land
- - - - occupied area

DIMENSIONS in mm

P1	P2	Ay	By	C	D1	D2	Gx	Gy	Hx	Hy
0.400	0.430	7.200	4.500	1.350	0.240	0.300	9.810	5.300	11.800	7.450